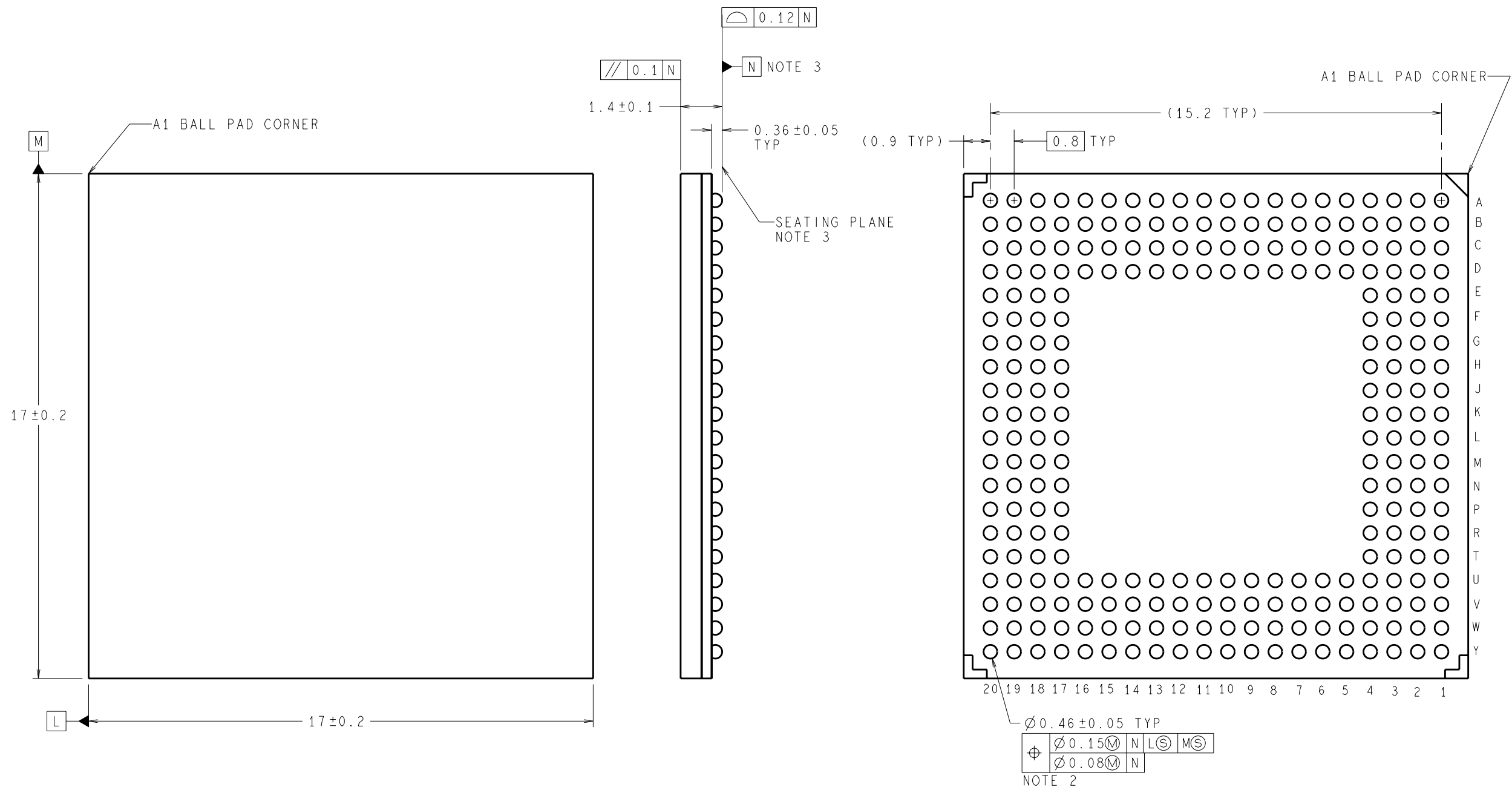


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	207	12/07/2000	MS/JS
B	BALL ROW Y WAS X; UPDATE NOTE 4.	241	03/19/2001	MS/JS



**DIMENSIONS ARE IN MILLIMETERS**

NOTES: UNLESS OTHERWISE SPECIFIED

- SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
- DIMENSION MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
- PRIMARY DATUM N AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- REFERENCE JEDEC REGISTRATION MO-205, VARIATION AM.

APPROVALS		DATE		 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN <b>MARTA SUCHY</b>		12/07/2000			
DFTG. CHK. THANH LEQUANG		03/19/2001		<b>FBGA, PLASTIC, LAMINATED,          17 X 17 X 1.4mm BODY,          256 BALL, 0.8mm PITCH</b>	
ENGR. CHK. JEFF SCHAEFER		03/19/2001			
 PROJECTION INCH [MM]		SCALE N/A	SIZE C	DRAWING NUMBER (SC)MKT-SLC256A	REV B
DO NOT SCALE DRAWING				SHEET 1 of 1	